

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.4131	100.0	0.48
				Subtotal	0.4131	100
Wire	Impurity	Non hazardous		0	0.01	0
	Pure metal	Copper (Cu)	7440-50-8	0.02959	99.99	0.03438
				Subtotal	0.02959	100
Die Attach		Aromatic Polyester Resin	60088-52-0	0.0028	2.5	0.00325
		Paraffin wax	8002-74-2	0.00783	7.0	0.0091
		Epoxy resin system		0.02238	20.0	0.026
		Silver (Ag)	7440-22-4	0.07888	70.5	0.09165
				Subtotal	0.11189	100
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02627	0.05	0.03053
	Copper alloy	Zinc (Zn)	7440-66-6	0.05254	0.1	0.06105
	Copper alloy	Iron (Fe)	7439-89-6	1.20845	2.3	1.40415
	Copper alloy	Copper (Cu)	7440-50-8	51.25401	97.55	59.55427
				Subtotal	52.54127	100
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.49056	100.0	0.57
				Subtotal	0.49056	100
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.6962	1.5	0.80895
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.40929	9.5	5.12335
	Filler	Silica fused	60676-86-0	40.84397	88.0	47.4584
	Carbon Black	Carbon black	1333-86-4	0.46414	1.0	0.5393
				Subtotal	46.4136	100
				Total	100.00001	100
						116.19438

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